

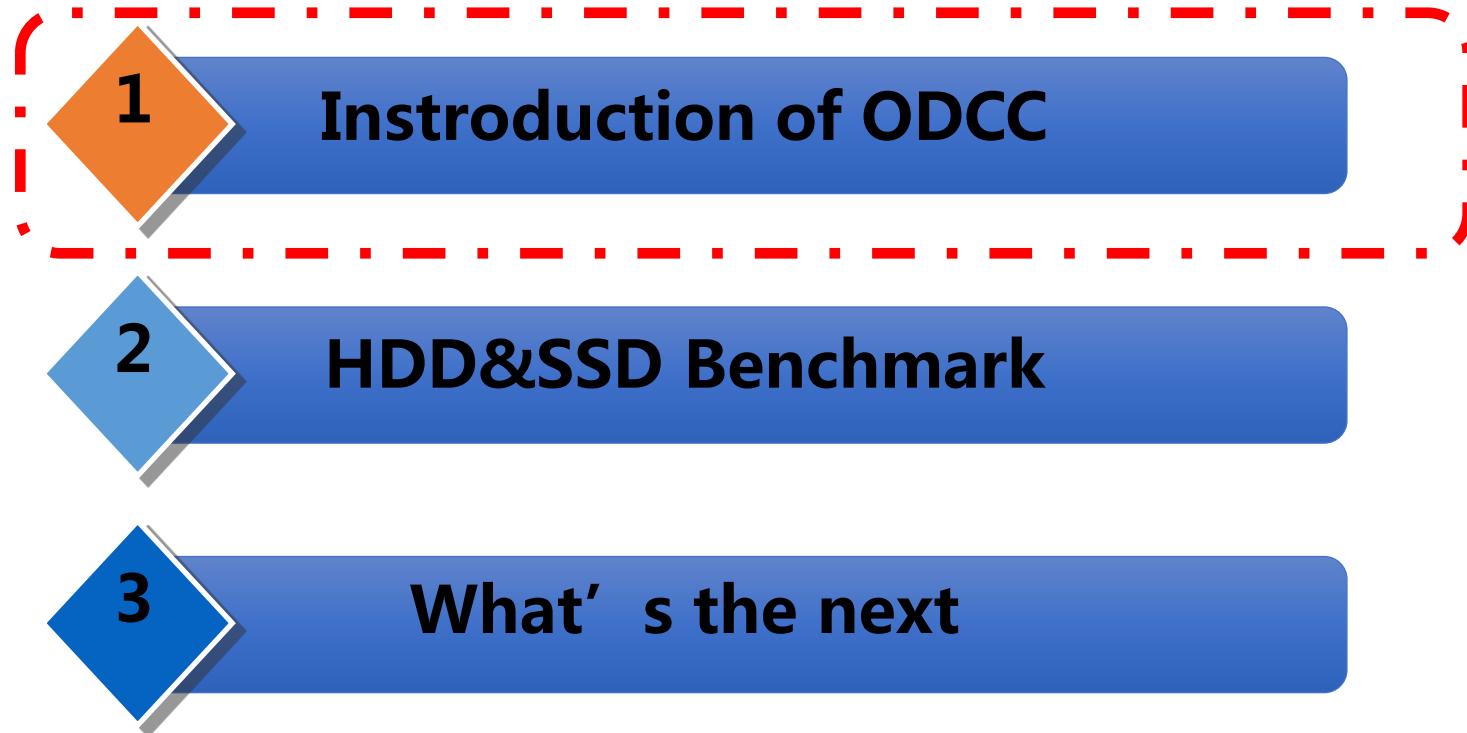
spec[®]

SPEC 2016亚洲峰会
SPEC 2016 ASIA SUMMIT

HDD&SSD Benchmark in China

Guo Liang

Test&Certify Working Group, ODCC

- 
- 1** **Instroduction of ODCC**
 - 2** **HDD&SSD Benchmark**
 - 3** **What' s the next**

ODCC:Open DataCenter Committee

Purpose

To promote the standard of server, data centers and other **industries unified specification**

To create an active, efficient and international competitiveness of the **ecological circle and open platform**

To promote industrial cooperation, innovation and new **technology applications**





Organization Structure

Secretariat

BOARD

Consultant

Server WG

Scorpio Rack server 2.0

Scorpio Rack Server 3.0

Scorpio Multi-node server

Datacenter WG

Module Data Center

Power module of IDC

Monitoring module of IDC

Site selection white paper

Model of operation and maintenance maturity

Network WG

AOC cable

Data center optical module

TOR 25G switch

Network operation and monitoring system

Virtual switch

SDN controller

Test&Certify WG

Scorpio rack server

Module data center

Scorpio multi node server

Enterprise Disk Benchmark

AOC



ODCC 2016 Summit



人民邮电报
CNII中国信息产业网
C114中国通信网
新华网
Pchome
DOIT
慧聰网

机房360
集微网-老查吧
金融界
贸讯网
企业网
泰尔网
通信产业网

通信世界网
网易新闻
物联中国
移动信息化
现代数据中心网
CIO时代
中国信息主管网

众视网
TechTarget中国
D电科技
至顶网
51CTO
CSDN
电脑商情网

IT168
Watchstor
天极
太平洋
比特网
中国信息化周报
中国计算机报

1

Instroduction of ODCC

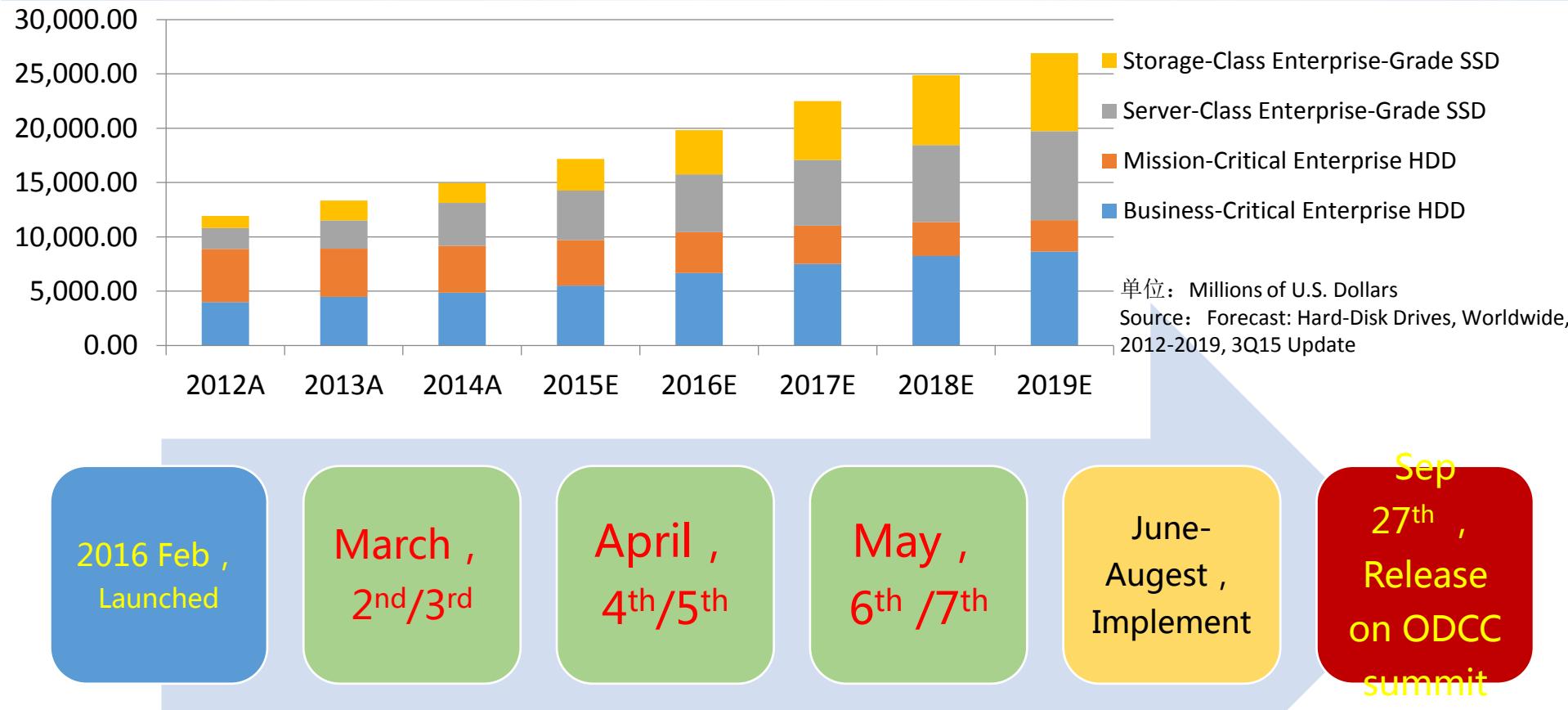
2

HDD&SSD Benchmark

3

What' s the next

Benchmark Schedule



Participating Units :

Alibaba Tencent Baidu China-Telecom China-Mobile China-UnionPay CAICT
Intel Samsung Seagate Toshiba Lite-On WD Lenovo Inspur IBM Huawei ZTE H3C Sugon



Benchmark Primary Coverage

No.	content	purpose
1	Performance test	<ul style="list-style-type: none">➤ IOPS➤ Throughput➤ Long time write (SSD only)➤ Cross Long time write (SSD only)
2	Stability test	<ul style="list-style-type: none">➤ 48hours➤ Copy and Compare➤ Temperature test➤ Air pressure environment
3	Compatibility test	<ul style="list-style-type: none">➤ Windows Compatibility➤ Linux Compatibility
4	Power test	<ul style="list-style-type: none">➤ Power on test (HDD only)➤ Power test under load➤ Energy efficiency test



Practice of HDD Benchmark

lenovo联想

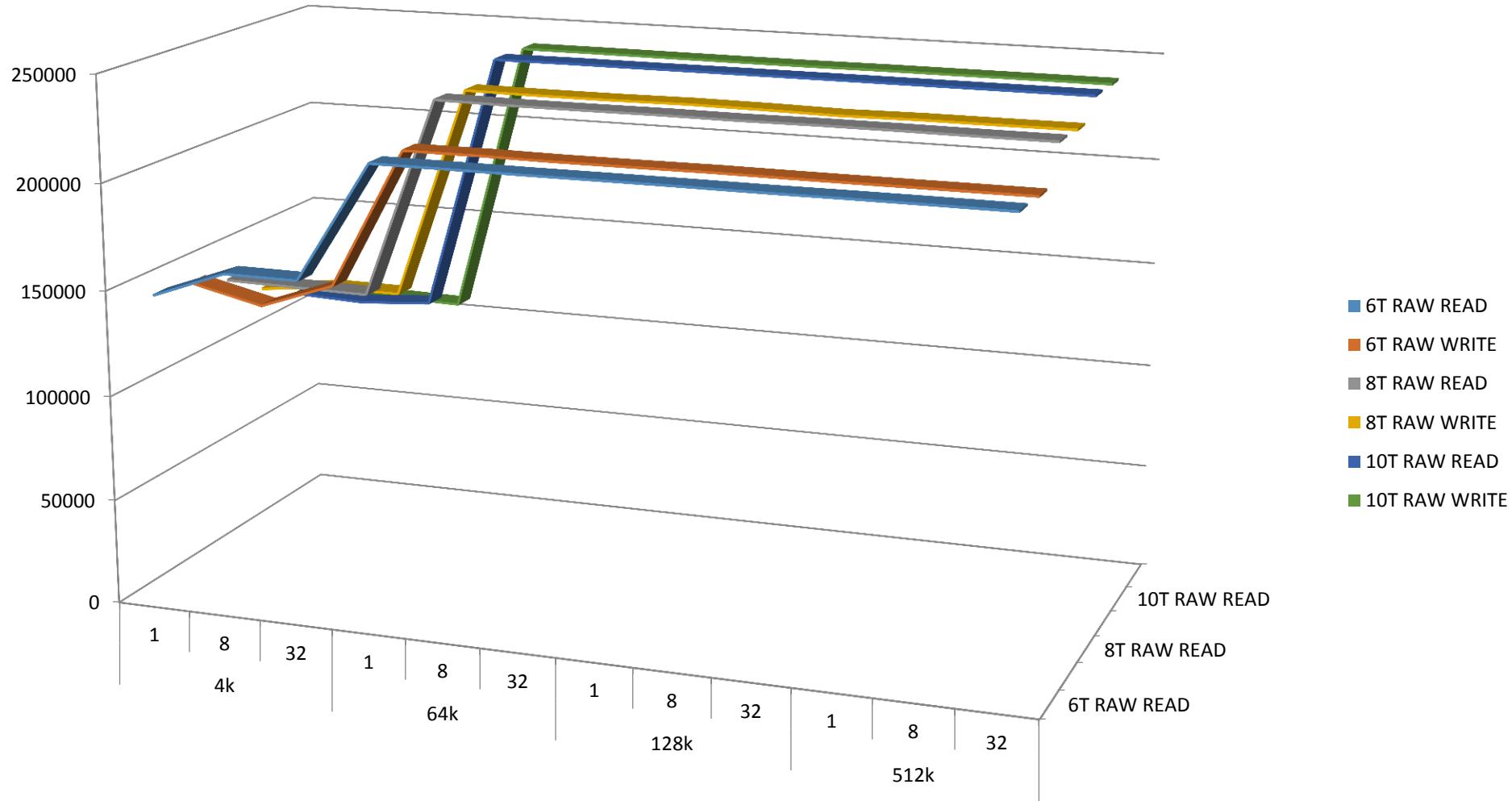
No.	Content	Test bed
1	Server name	ThinkServer RD450X
2	Os	Redhat Enterprise Linux Server release 7.0 (Maipo)
3	Software	Fio-2.2.12
4	CPU	Intel(R) Xeon(R) CPU E5-2690 v4 @ 2.60GHz 55核
5	Memory	32G
6	Mainboard	R450X MB(Rev 1.3)
7	Other software	Hdparm/Smartctl
8	BIOS version	R450X206
9	Network card	Intel Corporation I350 Gigabit Network Connection(rev 01)

TOSHIBA

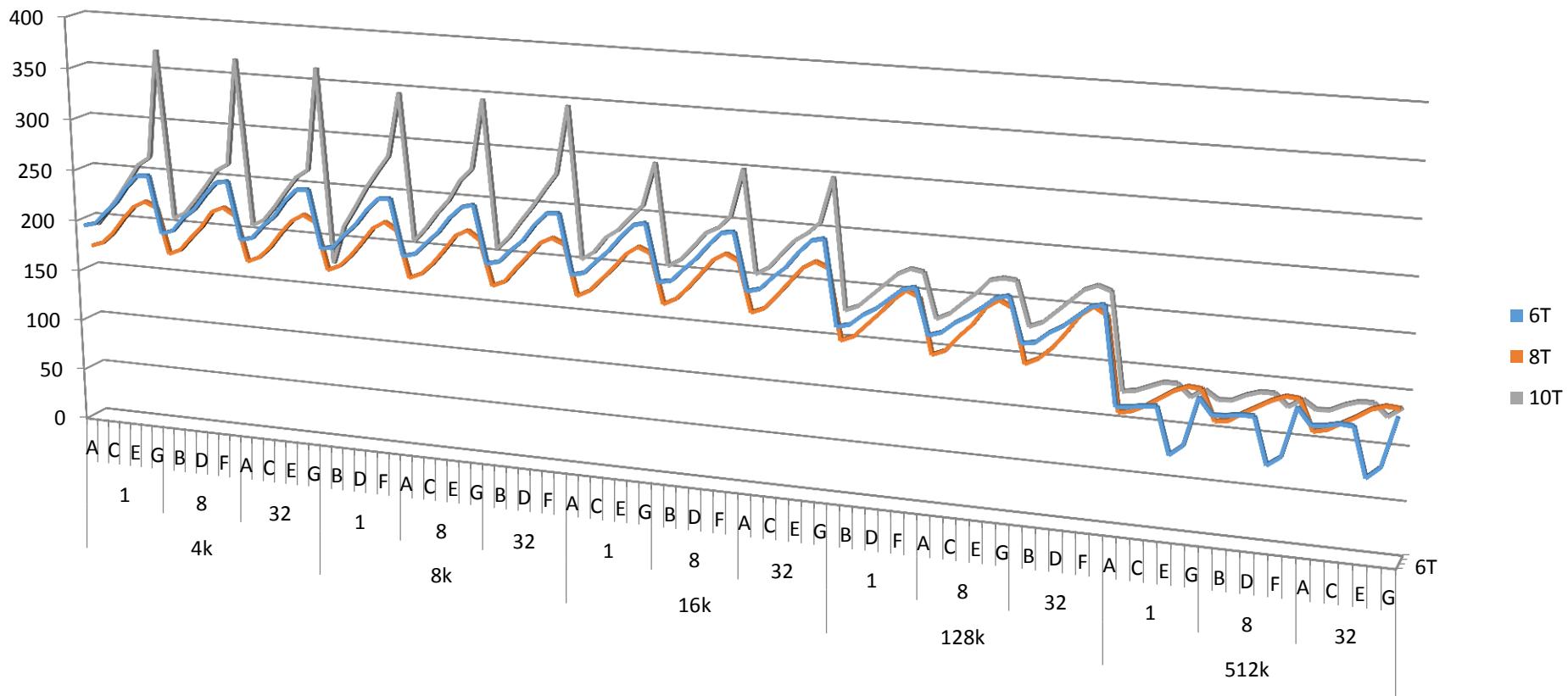
 SEAGATE

No.	Content	6T	8T	10T
1	Vendor	Toshiba	Seagate	Seagate
2	Model	MG04ACA600E	ST8000NM0055	ST10000NM0086
3	Capacity	6000GB	8000GB	10TB
4	Interface and rate	SATA 3.1/ 6.0Gbps	SATA 3.1/ 6.0Gbps	SATA 3.1/ 6.0Gbps

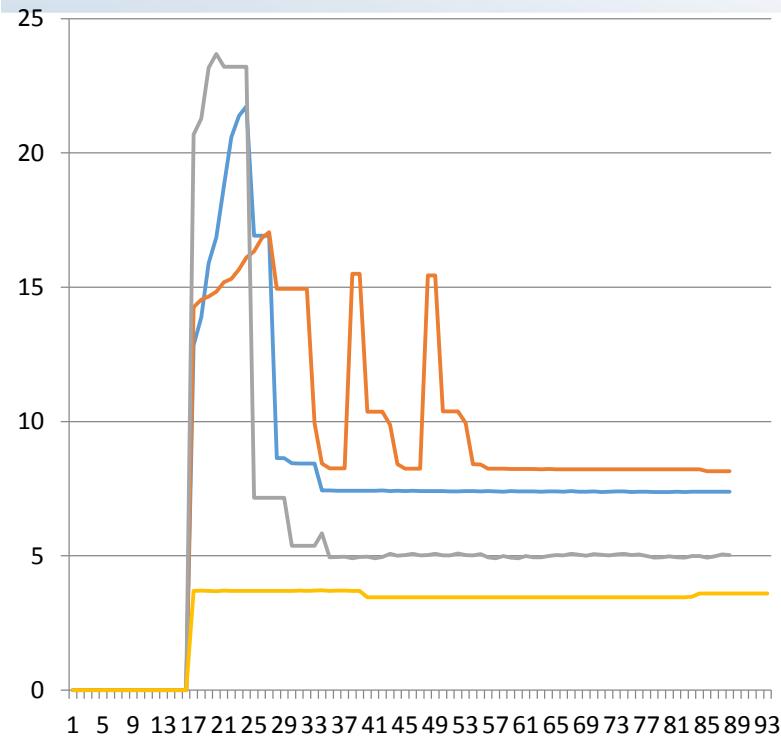
Throughput of HDD



IOPS of HDD

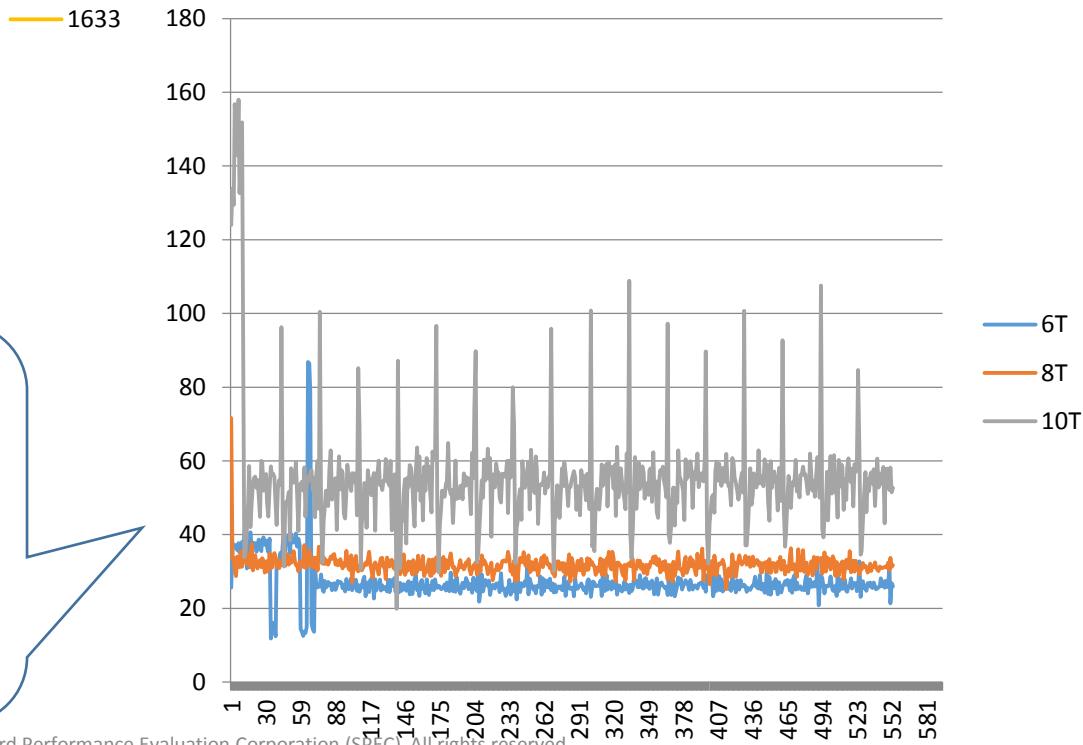


Power of HDD



- 10T average power consumption 5.85W; 8T average power consumption 9.23W; 6T average power consumption 9.97W
- 10T energy efficiency is larger

- HDD boot power ranging from 17-23W;
- SSD no power on burst



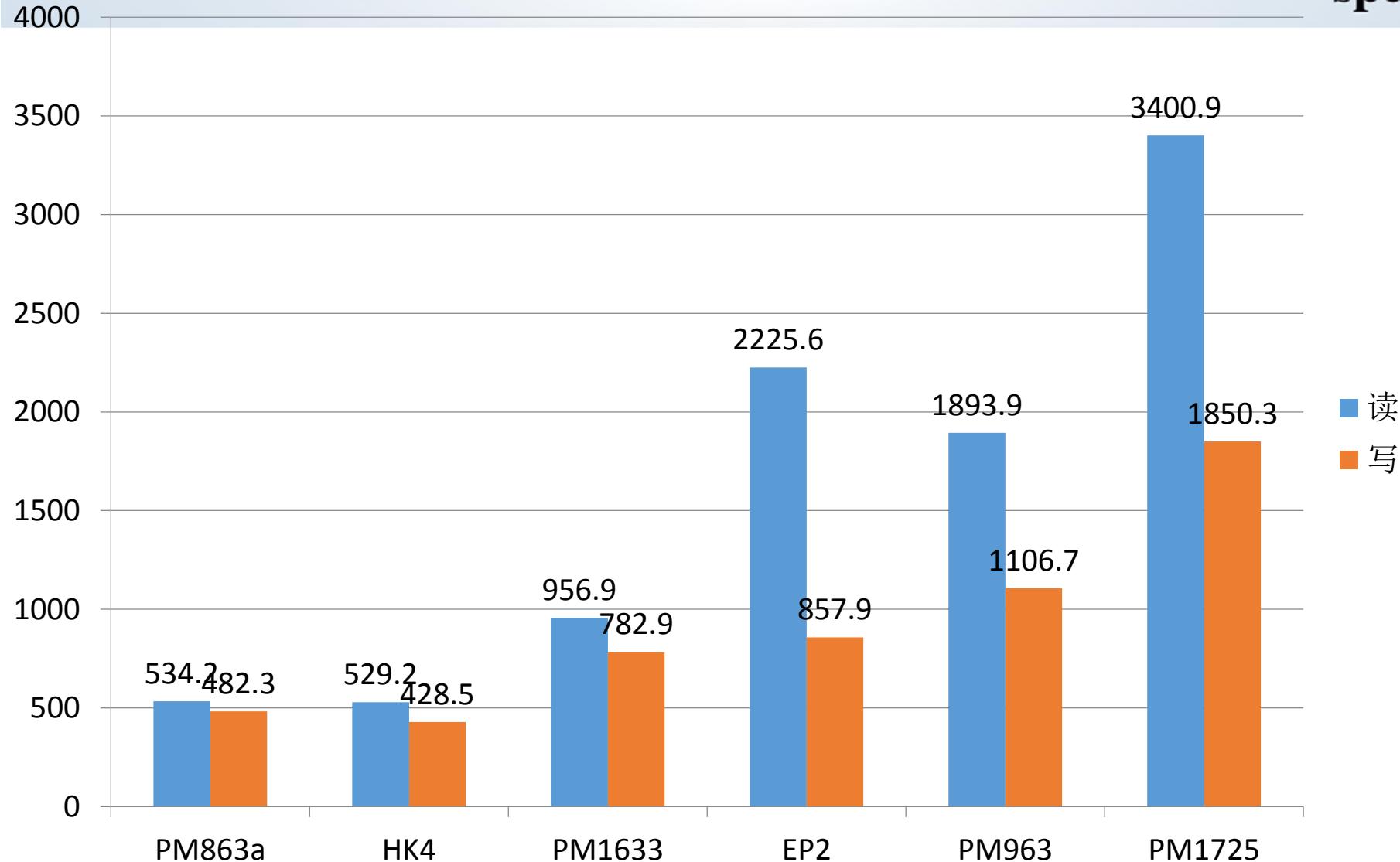


Practice of SSD Benchmark

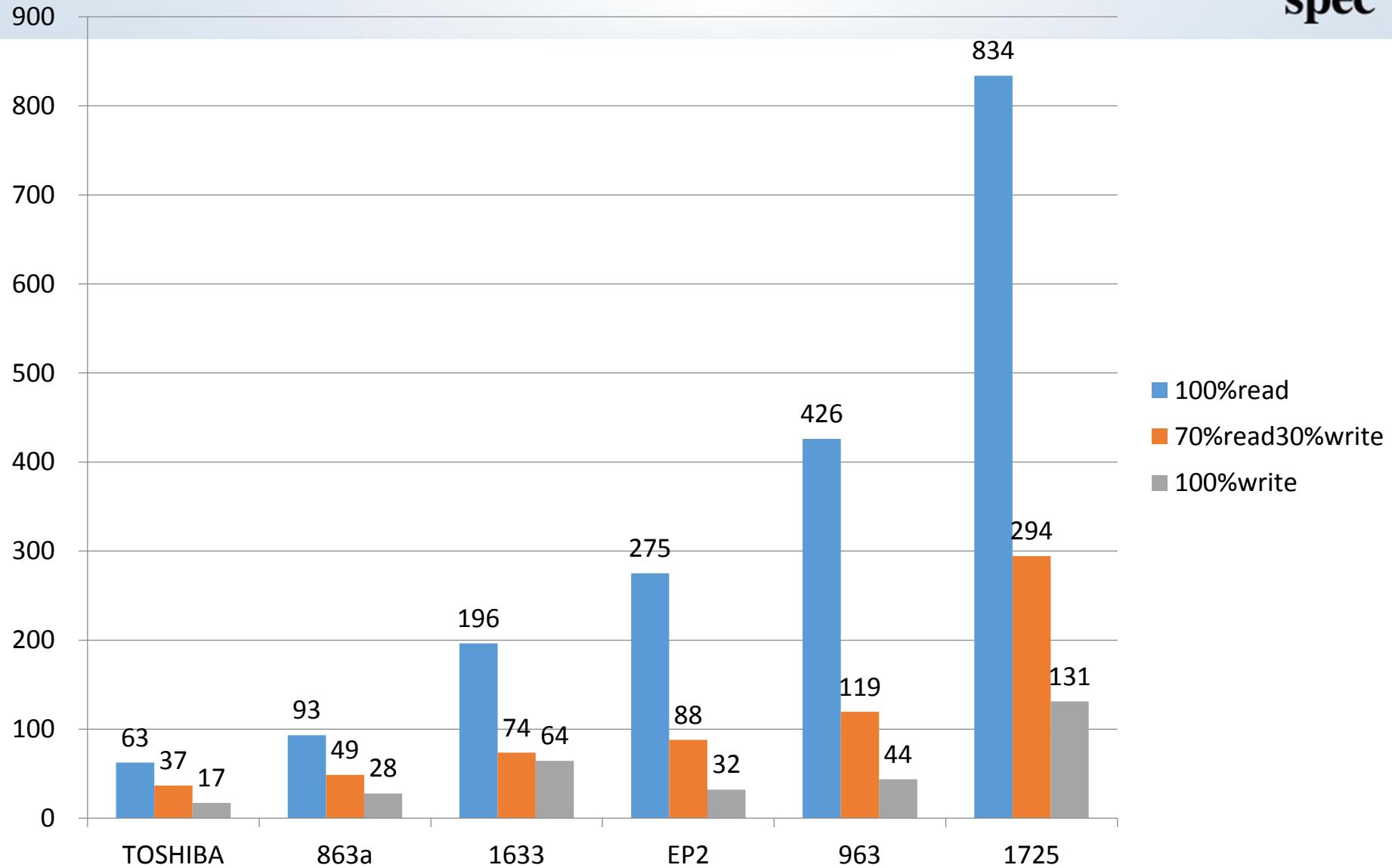
SAMSUNG **TOSHIBA** **LITEON®**

No.	Content	Product Information					
		Samsung	Samsung	Samsung	Samsung	Toshiba	Liteon
1	Vendor	Samsung	Samsung	Samsung	Samsung	Toshiba	Liteon
2	Model	PM863a	PM1633	PM1725	PM963	THNSN81Q9 2CSE	EP2-KP960
3	Size	2.5	2.5	2.5	2.5	2.5	M.2
4	Capacity	3.84TB	1.6TB	1.6TB	1.92TB	1.92TB	960GB
5	Interface and rate	SATA 3.1/ 6.0Gbps	SAS 12Gbps	PCIE3.0 x4 32Gbps	PCIE3.0 x4 32Gbps	SATA 3.1/ 6.0Gbps	M.2 PCIE3.0 x4 32Gbps
6	NAND type	3D V3 TLC	3D V3 TLC	3D V2 TLC	3D V3 TLC	15nm MLC	15 nm MLC

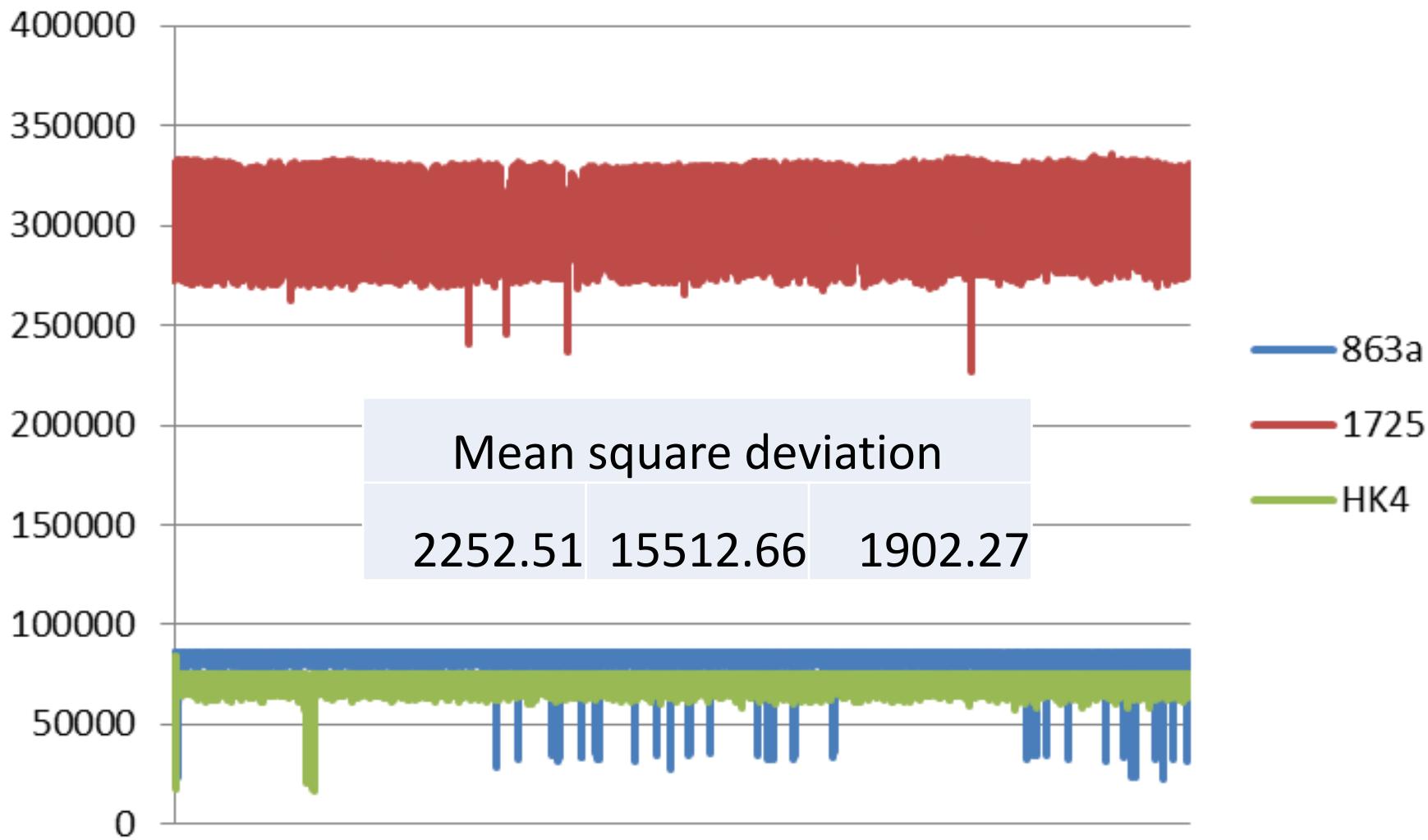
SSD throughput: 512k sequence



SSD IOPS: 4k random



Long time write-4k random@24hours



Cross long time write



1024K sequence+8k random+1024k sequence

A large orange diamond shape pointing towards the text "Introduction of ODCC".

1

Instruction of ODCC

A large blue diamond shape pointing towards the text "HDD&SSD Benchmark".

2

HDD&SSD Benchmark

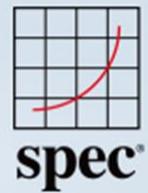
A large blue diamond shape pointing towards the text "What's the next".

3

What's the next

Programs





Members

Core member



Tencent 腾讯



Regular Member



英业达
Inventec



TOSHIBA

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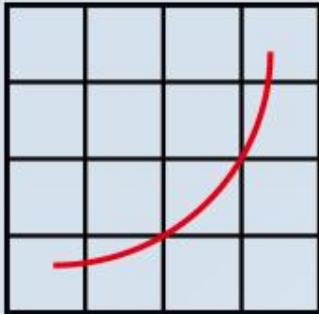
国网信通产业集团北京中电普华公司
BUILDING CHINA POWER INFORMATION TECHNOLOGY CO., LTD.
STATE GRID INFORMATION & TELECOMMUNICATION GROUP

AcBel 康舒科技
ACBEL POLYTECH INC.



Amphenol FCI





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Thank you!

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郭亮

ODCC测试认证工作组

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